

THIS SHEET HAS BEEN  
REPLACED

## **A PRECONDITIONER FOR A POLISHING PAD AND METHOD FOR USING THE SAME**

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### **Abstract of the Disclosure**

10 A preconditioning plate (10) prepares the surface of a  
polishing pad (24) to prepare the pad's surface for subsequent  
metal polishing of semiconductor wafers (27). The  
preconditioning plate has at least three intersecting radial ridges  
(14) on its surface and is made from a rigid plastic material. The  
15 preconditioning plate is rotated relative to the surface of the  
polishing pad prior to actual polishing to provide a uniform and  
stable polishing surface. The preconditioning plate does not  
abrade or wear away the polishing pad, nor does it form grooves in  
the polishing pad. Additionally, the preconditioning plate is  
reusable.

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